

EVAFLEX® 5

Part No. 20818-0**E

Product Specification

Qualification Test Report No. TR-20035

| Rev. | ECN | Date | Prepared by | Checked by | Approved by |
|------|--------|-------------------|--------------|------------|-------------|
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1. Scope

This product specification defines the test conditions and the performances of the EVAFLEX 5 Connector , shield FPC/FFC to board connector of 0.5mm pitch.

2. Product Name and Parts No.

2.1 Product Name

EVAFLEX 5

2.2 Parts No.

20818-0**E

3. Rating

3.1 Operating Conditions

Amperage: 0.3A AC/DC (per contact)

※In case of applying 0.5A/pin, the total current of the whole connector shall be 15.0A or lower.

※In case of applying 0.6A/pin, the total current of the whole connector shall be 12.0A or lower.

Voltage: 200V AC/DC

Operating temperature: 233 to 358K(-40°C to 85°C) (Containing temperature rise by current)

Operating humidity: 85% max

3.2 Storage Conditions

Storage temperature: 248 to 333K(-25°C to 60°C)

Storage humidity: 85% max. (Non-condensing)

4. Test and Performance

Test Condition

This initial test is equal to it's at shipping condition and unless otherwise specified, all tests and measurements shall be performed under the following conditions in accordance with MIL-STD-202.

Temperature: 288K to 308K(15°C to 35°C)

Pressure: 866hPa to 1066hPa(650mmHg to 800mmHg)

Relative humidity: 45 to 75% R.H.

4.1. Electrical Performance

| No | Items | Test Conditions | Specifications |
|----|---------------------------------|---|--|
| 1. | Contact Resistance | Solder the connector to the test board and connect the applicable Lead. Apply the open circuit voltage of 20mV MAX. DC and the closed circuit current of 10mA MAX. DC in accordance with MIL-STD-202 Method 307. Measure the contact resistance as shown in Fig.1 by the four terminals method. | Initial : 60mΩ or less Change ΔR : 40mΩ or less |
| 2. | Insulation Resistance | Solder the connector to the test board and connect the applicable Lead, then, apply DC100V between the neighboring contacts in accordance with MIL-STD-202, Method 302. | 100MΩ or more |
| 3. | Dielectric Withstanding Voltage | Solder the connector to the test board and connect the applicable Lead, then, apply AC 250V (rms) between the neighboring contacts for 1 minute in accordance with MIL-STD-202, Method 301. | No abnormalities such as creeping discharge, flashover, insulator breakdown occur. |
| 4. | Temperature rise | Solder the connector to the test board and connect the applicable Lead, then, apply the rating current to each contact and measure temperature rise around the connector. | Temperature rise T : 30K (30°C) MAX. |
| 5. | Differential Impedance | Solder the connector to the test board and connect the applicable Lead, then, measure differential impedance with the rise time 250psec. | 100±10Ω |

4.2. Mechanical Performance

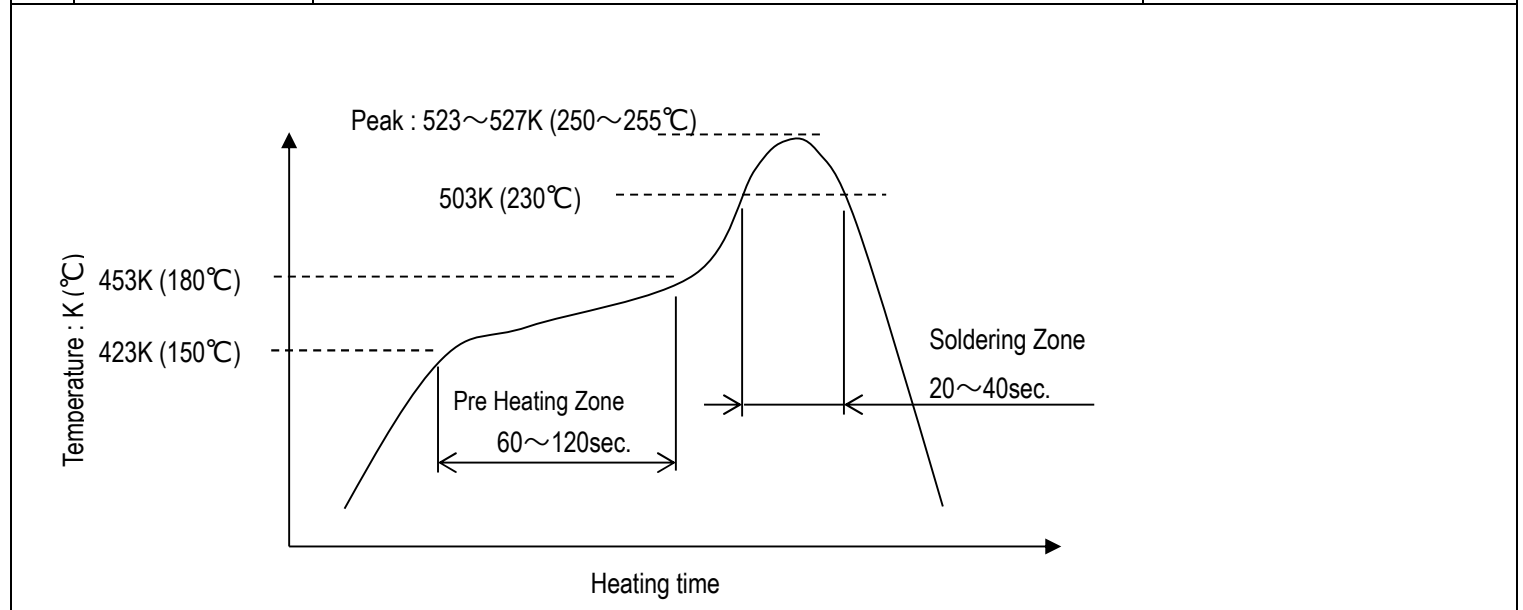
| No | Items | Test Conditions | Specifications |
|----|----------------------------|---|--|
| 1. | Mating and Un-mating Force | Solder the connector to the test board and connect the applicable Lead, then, set the specimen on push-on/pull-off machine. Measure the force at initial and mating/un-mating 30th cycles at a speed of 25±3mm/min. along the mating axis. | <u>Mating Force</u> 41P : 29.2N MAX. 51P : 30N MAX. <u>Un-mating Force</u> 41P : 4.25N MIN. 51P : 5N MIN. |
| 2. | Durability | Solder the connector to the test board and set the specimen on the push-on/pull-off machine. Mate and un-mate 30cycles repeatedly at a speed of 25±3mm/min. along the mating axis. | [Contact Resistance] Shall meet 4.1.1. |
| 3. | Contact Retention Force | Set the connector on the push-on/pull-off machine and apply force to the contact in the direction opposite to insertion at a speed of 25±3mm/min. Measure the force when the contact came off from the connector. | 0.5N / Pin MIN. |
| 4. | FPC/FFC Retention Force | Solder the connector to the test board and connect the applicable Lead, then, set the specimen on push-on/pull-off machine. Pull the Lead along the mating axis. | 41P : 22N MIN. 51P : 25N MIN. No abnormality in the lock part appearance. |
| 5. | Vibration | Solder the connector to the test board and connect the applicable Lead, then, set them on the vibrator and apply the following vibration in accordance with MIL-STD-202, Method 201. During test, apply 100mA DC to check electrical discontinuity. Frequency : 10Hz→55Hz→10Hz/approx 1min. Directions : Three mutually perpendicular direction. Total Amplitude : 1.52mm Sweep duration : 2 hours for each direction, a total of 6 hours. | [Contact Resistance] Shall meet 4.1.1. [Electrical discontinuity] No electrical discontinuity grater than 1µs. [Appearance] No abnormality adversely affecting the performance shall occur. |
| 6. | Shock | Solder the connector to the test board, connect the applicable Lead, and set them on the shock machine. Apply the following shock in accordance with MIL-STD-202, Method 213, Condition A. During test, apply 100mA DC to check electrical discontinuity. MAX.G : 50G Duration : 11msec Wave Form : Half Sinusoidal Test times : 3 times for each direction,(a total of 18 times.) | [Contact Resistance] Shall meet 4.1.1. [Electrical discontinuity] No electrical discontinuity grater than 1µs. [Appearance] No abnormality adversely affecting the performance shall occur. |

4.3. Environmental Performance

| No | Items | Test Conditions | Specifications |
|----|-------------------------|---|--|
| 1. | Thermal Shock | Solder the connector to the test board and connect the applicable Lead, then, expose them to the following environment in accordance with MIL-STD-202, Method 107, Condition A. Temperature : 218K(-55°C) : 30min.→358K(85°C) : 30min. Transition time : 5min. MAX. No. of cycles : 5 cycles | [Contact Resistance] Shall meet 4.1.1. [Insulation Resistance] Shall meet 4.1.2. [Dielectric Withstanding Voltage] Shall meet 4.1.3. [Appearance] No abnormality adversely affecting the performance shall occur. |
| 2. | High Temperature Life | Solder the connector to the test board and connect the applicable Lead, then, expose them to the following environment in accordance with MIL-STD-202, Method 108, Condition B. Temperature : 358±2K (85±2°C) Duration : 250 hours | [Contact Resistance] Shall meet 4.1.1. [Appearance] No abnormality adversely affecting the performance shall occur. |
| 3. | Humidity (Steady State) | Solder the connector to the test board and connect the applicable Lead, then, expose them to the following environment in accordance with MIL-STD-202, Method 103, Condition A. Temperature : 313±2K (40±2°C) Humidity : 90~95%RH Duration : 240 hours | [Contact Resistance] Shall meet 4.1.1. [Insulation Resistance] Shall meet 4.1.2. [Dielectric Withstanding Voltage] Shall meet 4.1.3. [Appearance] No abnormality adversely affecting the performance shall occur. |
| 4 | Humidity (Cycling) | Solder the connector to the test board and connect the applicable Lead, then, expose them to the following environment in accordance with MIL-STD-202, Method 106. Temperature : 298~338K (25~65°C) Humidity : 90~98%RH Duration : 10cycles (240hours) | [Contact Resistance] Shall meet 4.1.1. [Insulation Resistance] Shall meet 4.1.2. [Dielectric Withstanding Voltage] Shall meet 4.1.3. [Appearance] No abnormality adversely affecting the performance shall occur. |
| 5 | Salt Water Spray | Solder the connector to the test board and connect the applicable Lead, then, expose them to the following environment in accordance with MIL-STD-202, Method 101, Condition B. Temperature : 308±2K (35±2°C) Salt water density : 5±1% [by weight] Duration : 48 hours | [Contact Resistance] Shall meet 4.1.1. [Appearance] No abnormality adversely affecting the performance shall occur. |
| 6 | H ₂ S Gas | Solder the connector to the test board and connect the applicable Lead, then, expose them to the following environment. Temperature : 313±2K (40±2°C) Relative Humidity : 80±5%RH Gas : H ₂ S 3±1ppm Duration : 48 hours | [Contact Resistance] Shall meet 4.1.1. [Appearance] No abnormality adversely affecting the performance shall occur. |

4.4. Others

| No | Items | Test Conditions | Specifications |
|----|---------------------------|--|--|
| 1 | Solderability | Dip the soldering tip of the contact in the solder bath at $518 \pm 5K$ ($245 \pm 5^\circ C$) for 5 ± 0.5 seconds. Use RMA or R type flux and immerse for 5 to 10 seconds in accordance with MIL-STD-202, Method 208. | More than 95% of the dipped surface shall be evenly wet. |
| 2 | Soldering Heat Resistance | <u>Reflow part</u> Peak : $523 \sim 528K$ ($250 \sim 255^\circ C$) $503K$ ($230^\circ C$) MIN. : $20 \sim 40$ sec. <u>Pre-heat part</u> $423 \sim 453K$ ($150 \sim 180^\circ C$) : $60 \sim 120$ sec. Reflow shall be within twice. Refer to Reflow temperature profile. | No abnormality adversely affecting the performance. |

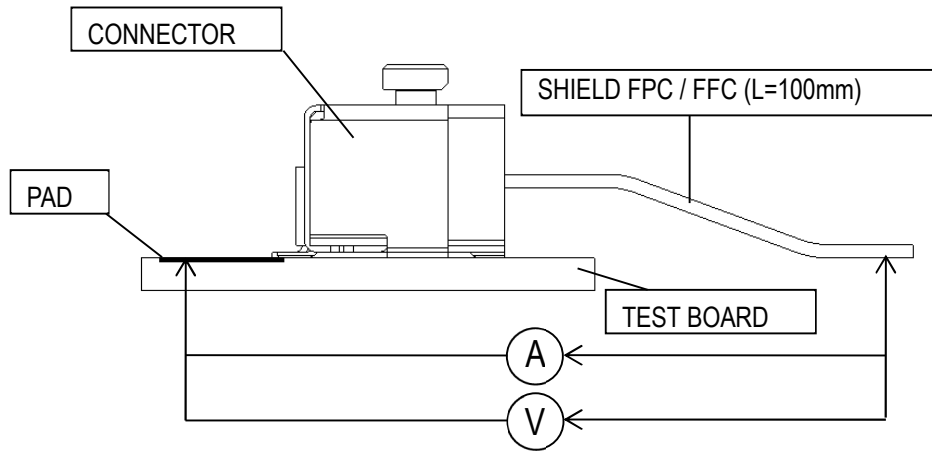


4.5 Test Sequence and Specimen Quantity

Table.1 Test Sequence and Sample Quantity

| Test Item | Group | | | | | | | | | | | | | |
|---------------------------|-------|---|-----|----|---|-------|-----|-----|-----|-----|-----|-----|----|----|
| | A | B | C | D | E | F | G | H | J | K | L | M | N | P |
| Contact Resistance | | | 2,6 | | | 1,3,5 | 1,3 | 1,3 | 1,5 | 1,5 | 1,3 | 1,3 | | |
| Insulation Resistance | | | | | | | | | 2,6 | 2,6 | | | | |
| D. W. Voltage | | | | | | | | | 3,7 | 3,7 | | | | |
| Temp. Rise | 1 | | | | | | | | | | | | | |
| Differential Impedance | | 1 | | | | | | | | | | | | |
| Mating Force | | | 1,5 | | | | | | | | | | | |
| Un-mating Force | | | 3,7 | | | | | | | | | | | |
| Durability | | | 4 | | | | | | | | | | | |
| Contact Retention Force | | | | 1 | | | | | | | | | | |
| FPC/FFC Retention Force | | | | | 1 | | | | | | | | | |
| Vibration | | | | | | 2 | | | | | | | | |
| Shock | | | | | | 4 | | | | | | | | |
| Thermal Shock | | | | | | | 2 | | | | | | | |
| High Temperature Life | | | | | | | | 2 | | | | | | |
| Humidity (Steady State) | | | | | | | | | 4 | | | | | |
| Humidity (Cycling) | | | | | | | | | | 4 | | | | |
| Salt Water Spray | | | | | | | | | | | 2 | | | |
| H ₂ S Gas | | | | | | | | | | | | 2 | | |
| Solderability | | | | | | | | | | | | | 1 | |
| Soldering Heat Resistance | | | | | | | | | | | | | | 1 |
| Sample QTY. | 5 | 5 | 5 | 20 | 5 | 5 | 5 | 5 | 5 | 5 | 5 | 5 | 10 | 10 |

※Numbers indicate test sequences.



Contact Resistance= R_{AB} – (FPC / FFC 100mm (Conductor Resistance))

Fig.1 Contact Resistance

5. Recommended Metal Mask

Refer to drawing for the recommended metal mask thickness and opening dimension.